

FEATURES

Surface Mounting Design 5.4*5.4*5.0mm

High Current Handling Capability 5000A @ 8/20 µs

Low Capacitance and Insertion Loss

Quick Response and Long Service Life

Moisture sensitivity level: Level 1



5.4*5.4*5.0mm



APPLICATION INFORMATION

| Communication equipment. | |
|---------------------------------|--|
| Repeaters, Modems | |
| Telephone Interface,Line cards. | |
| Data communication equipment. | |

AGENCY APPROVALS

| lcon | Solderability | | |
|------------|------------------------------------|--|--|
| RoHS | Compliance with 2011/65/EU | | |
| HF | Compliance with IEC61249-2-21:2003 | | |
| P 6 | Mean lead free | | |
| IR. | UL Certificated E505857 | | |

PRODUCT CHARACTERISTICS

| Lead Material | Body Material | Terminal Finish | |
|-----------------------|---------------|-----------------------|--|
| Copper or Fe-Ni alloy | Ceramics | 100% Matte-Tin Plated | |



ELECTRICAL PARAMETER

| Parameter | Condition | Rating | | |
|-----------------------------------|-----------------------|--------------------------------------|----|--|
| DC Spark-over Voltage 1) | 100V/s | 336-504 | | |
| Impulse Spark-over Voltage | At 1kV/μs | for 99 % of measured values ≤1100 | V | |
| impuise Spark-over voltage | At 1kV/μs | Typical values of distribution ≤1000 | | |
| Discharge Current (8/20us) 2) | 10 times | 5 | KA | |
| AC Discharge Current | 50Hz, 1S | 5 | Α | |
| Minimum Insulation Resistance | Test Voltage DC=100V | 1 | | |
| Max. Capacitance 1MHz | V _{DC} =0.5V | 1 | | |
| Operating and Storage Temperature | | -40~125 | °C | |

¹⁾ In ionized mode

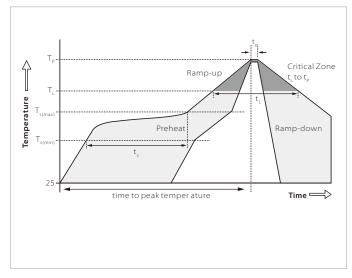
ENVIRONMENTAL RELIABILITY CHARACTERISTICS

| Testing items | Technical standards | |
|-------------------------------|---|--|
| High Temperature Storage Test | Temperature: 85°C ; Time:2H | |
| Low Temperature Storage Test | Temperature: -40°C ; Time:2H | |
| Vibration | Frequency: 10-500Hz ; Amplitude: 0.15mm ; Time:45min | |
| Resistance of soldering heat | Temperature: 260±5°C; Time of dip soldering: 10s, 1time | |

NOTE: Up-screen program can be specified by customer's request via contacting Semiware service

REFLOW PROFILE

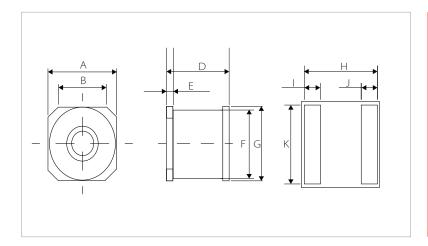
| Reflow Condition | | Lead-free assembly | |
|--|--|--------------------|--|
| | Temperature Min | 150°C | |
| Pre Heat | Temperature Max | 200°C | |
| | Time(min to max) | 60-180 secs | |
| Average ramp up rate (Liquidus)Temp (T_L) to peak T_s (max)to T_L - Ramp-up Rate | | 3°C/second max | |
| Reflow | Temperature (T _L) (Liquidus) | 217℃ | |
| Reliow | Temperature (T_L) | 60-150 seconds | |
| PeakTem | perature (T,) | 245~260°C | |
| Time within 5°C of actual peak Temperature (tp) | | 30 seconds | |
| Ramp-down Rate | | 6°C/second max | |
| Time 25°C to peak Temperature (T₀) | | 8 minutes max. | |
| Do not exceed | | 260°C | |



²⁾ Terms and waveforms in accordance with ITU-T Rec. K. 12; IEC 61643-21

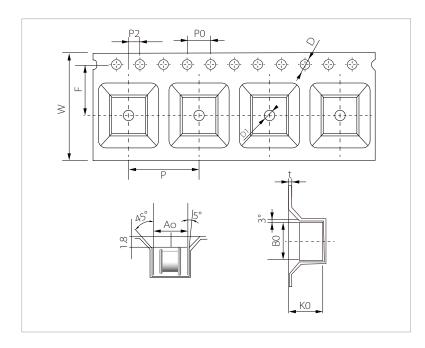


DIMENSIONS AND RECOMMENDED SOLDERING PAD



| Ref. | mm |
|------|----------|
| А | 5.4±0.1 |
| В | 3.8 |
| D | 5.0±0.2 |
| E | 0.5±0.1 |
| F | Ф5.0±0.1 |
| G | Ф5.4±0.1 |
| Н | 5.7 |
| I | 1.2 |
| J | 1.2 |
| K | 5.8 |

PACKAGE REEL INFORMATION



| Ref. | mm |
|------|----------|
| W | 16.0±0.3 |
| Р | 12.0±0.1 |
| F | 7.5±0.1 |
| P2 | 2.0±0.1 |
| D | 1.5±0.1 |
| D1 | 1.5±0.1 |
| PO | 4.0±0.1 |
| 10P0 | 40.0±0.2 |
| A0 | 5.7±0.1 |
| ВО | 5.7±0.1 |
| KO | 5.7±0.1 |
| t | 0.4±0.05 |

ORDERING INFORMATION

| Part Number | Size | Marking | QTY/Reel | Reel Size |
|-------------|---------------|--------------------------|----------|-----------|
| SG2R05B420A | 5.4*5.4*5.0mm | 愛 SG420 <u>05</u> | 800 | 13" |



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